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| Please use this form if you would like to apply for an internship at TSMP Law Corporation. Applications submitted via other channels will not be considered.  Fields marked with an asterisk (\*) are compulsory. All applications should also be **typewritten** and accompanied by a copy of your **latest academic transcript** setting out your law grades.  Please send your applications to: **internship@tsmplaw.com** | | | Please affix recent passport-sized photograph |
| **PERSONAL DETAILS** | | | |
| **Full Name\***  *(as in NRIC/Passport)*  *Surname in block letters* |  | | |
| **NRIC / Passport Number** *(last 4 alphanumeric characters)***\*** |  | | |
| **Nationality\*** |  | | |
| **Date of Birth\*** |  | | |
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| **CONTACT DETAILS** | | | |
| **E-mail address\*** |  | | |
| **Mailing address\*** |  | | |
| **Home phone number\*** |  | | |
| **Mobile phone number\*** |  | | |
| **Contact person in case of emergency** | *Name* |  | |
| *Number(s)* |  | |

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| **INTERNSHIP PREFERENCES** | | | | | | | | | |
| **Practice Areas**  *(Select 🗸 up to 3)* | | **Transactional** | | | | | **Dispute Resolution** | | |
| M&A / ECM | | | 🗖 | | Commercial Litigation / Arbitration | | 🗖 |
| Banking & Finance / Corporate Real Estate | | | 🗖 | | Construction | | 🗖 |
| No preference | | | 🗖 | | Crime | | 🗖 |
|  | | |  | | Restructuring & Insolvency | | 🗖 |
|  | | |  | | No preference | | 🗖 |
| **Period of attachment\***  *Please select 🗸* | | May – September | | | 🗖 | | | | |
| December – January | | | 🗖 | | | | |
| **Special requests / Available dates** | |  | | | | | | | |
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| **ACADEMIC QUALIFICATIONS** (Please enclose latest academic transcript) | | | | | | | | | |
| **Year of study and school\*** | |  | | | | | | | |
| **Year of graduation\*** | |  | | | | | | | |
| **Degree programme\*** | |  | | | | | | | |
| **Awards and scholarships\*** | |  | | | | | | | |
| **Law subjects and grades\*** | | *Law Subject* | | | | | | *Grade* | |
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| **WORK / INTERNSHIP EXPERIENCE** | | | | | | | | | |
| ***Organisation*** | ***Time Period*** | | | ***Position*** | | ***Description*** | | | |
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| **WHAT IS THE SINGLE MOST IMPORTANT THING YOU WOULD LIKE US TO KNOW ABOUT YOU?\*** | | | | | | | | | |
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| **NOTICE AND Consent IN RELATION TO THE Personal Data Protection Act** |
| By filling up this application form and sending it to TSMP Law Corporation (“**TSMP**”), I agree and consent to TSMP’s collection, use and/or disclosure of all the information provided herein for all purposes relevant to my internship application and any prospective internship with TSMP (including but not limited to evaluative and research purposes, and the purposes of managing or terminating any internship with TSMP). To the extent that I have provided personal data of individual(s) other than myself, I undertake that I have obtained all necessary consents from such individual(s) to the collection, processing, use and disclosure of their personal data by TSMP. |